

Docket No.: **JCLA31290**

Form 1595 (Rev. 09/04)

RECORDATION FORM COVER SHEETU.S. Department of Commerce
Patent and Trademark Office**PATENTS ONLY**

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

Names(s)

Liao, Kuo-Hsien

Date of Execution

Apr. 28, 2009

2. Name/address of receiving
Party(ies):**Advanced Semiconductor Engineering,
Inc.**26, Chin 3rd. Rd., 811, Nantze Export
Processing Zone, Kaohsiung, Taiwan,
R.O.C.3. Nature of conveyance: ☒ Assignment☐ Merger ☐ Security Agreement ☐ Other☐ Change of Name ☐ ReassignmentAdd'l name(s)/address(es) of receiving parties
Attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

A. Patent Application No. (s)

12/501,636

Additional numbers attached?

B. Patent No. (s)

☐ Yes ☒ No5. Name and address of party to whom
Correspondence concerning document
should be mailed:**J. C. Patents**
4, Venture Suite 250
Irvine, CA. 92618
Tel: (949) 660-0761
Fax: (949) 660-0809
E-mail: jcpj@email.msn.com6. Total No. of applications and patents
involved:

ONE(1)

7. Total fee (37 CFR §3.41): **\$40.00**☐ Authorized to be charge by credit card☒ Authorized to be charge to deposit account☐ Enclosed☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last Numbers _____

Expiration Date _____

b. Deposit Account Number **50-0710**Authorized User Name **Jiawei Huang**Atty Docket No.: **JCLA31290**

9. Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any
attached copy is a true copy of the original document.Jiawei Huang
Name of Person Signing
Registration No. 43,330
Signature7-13-2009
DateTotal number of pages
including cover sheet,
attachments, and
documents: **3**

CH \$40.00 500710 12501636

ASEK2226
31290-US-PA

ASSIGNMENT

WHEREAS,

1. Liao, Kuo-Hsien

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **CHIP PACKAGE AND MANUFACTURING METHOD THEREOF**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Advanced Semiconductor Engineering, Inc.
of 26, Chin 3rd. Rd., 811, Nantze Export Processing Zone, Kaohsiung, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

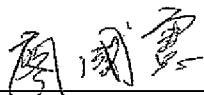
Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASEK2226
31290-US-PA

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: _____



Date: _____

2009 - 04 - 28

Sole or First Joint Inventor: Liao, Kuo-Hsien